PCN Number:	20231031005.1	**PCN Date:**	October 31, 2023
Title:	Qualification of RFAB using qualified Process Technology, Die Revision and Datasheet update for select devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	Jan 31, 2024	**Estimated Sample Availability:**	Dec 1, 2023*

***Sample requests received after December 1, 2023 will not be supported.**

Change Type:					
☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Materials
☐	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

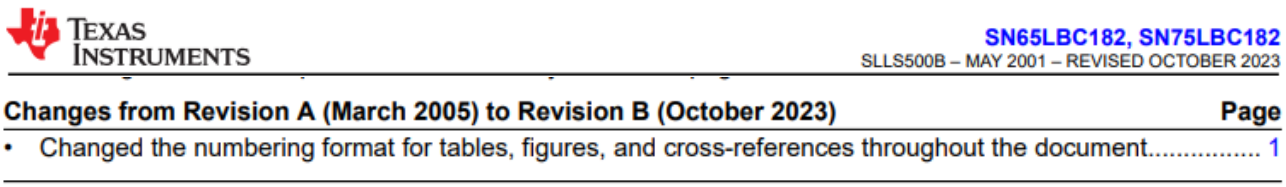
Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the LBC7 qualified process technology for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
DL-LIN	LBC2	150 mm	RFAB	LBC7	300 mm

The die was also changed as a result of the process change.

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



TEXAS INSTRUMENTS

SN65LBC182, SN75LBC182
SLLS500B – MAY 2001 – REVISED OCTOBER 2023

Changes from Revision A (March 2005) to Revision B (October 2023) **Page**

- Changed the numbering format for tables, figures, and cross-references throughout the document..... 1

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SNx5LBC182	SLLS500A	**SLLS500B**	http://www.ti.com/product/SN65LBC182

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
A	**A**

Sample product shipping label (not actual product label)

Product Affected:

SN65LBC182DR	SN65LBC182DRG4	SN65LBC182P	SN75LBC182DR

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN65LBC182DR	Qual Device: SN75LBC182DR	Qual Device: SN65LBC182P	QBS Reference (Package): TCAN1044VDRQ1 (PG2.0)	QBS Reference (Package): TCAN1044VDRQ1 (PG1.1/PG1.0)	QBS Reference (Process): TPS51217DSCR	QBS Reference (Process, Product): SN65HVD3080EDGSR	QBS Reference (Package): SN75179BP	QBS Reference (Package): TPS54231DR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	2/154/0	-	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	1/77/0	2/154/0	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	1/77/0	2/154/0	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0	2/90/0	-	-	-	-
HTOL	B1	Life Test	135C	635 Hours	-	-	-	-	-	3/231/0	-	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	-	-	-	-	1/76/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	-	-	-	-	1/76/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	-	-	-	-	3/66/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	-	-	-	-	-	3/15/0

Type	#	Test Name	Condition	Duration	Qual Device: SN65LBC182DR	Qual Device: SN75LBC182DR	Qual Device: SN65LBC182P	QBS Reference (Package): TCAN1044VDRQ1 (PG2.0)	QBS Reference (Package): TCAN1044VDRQ1 (PG1.1/PG1.0)	QBS Reference (Process): TPS51217DSCR	QBS Reference (Process, Product): SN65HVD3080EDGSR	QBS Reference (Package): SN75179BP	QBS Reference (Package): TPS54231DR
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	1/10/0	2/20/0	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	1/3/0	-	-	-	-	-	-
ESD	E2	ESD HBM (Bus Pins)	-	15000 Volts	1/3/0	-	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	3000 Volts	1/3/0	-	-	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	-	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	1/30/0	-	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device SN65LBC182DR is qualified at MSL1 260C
- Qual Device SN75LBC182DR is qualified at MSL1 260C
- Qual Device SN65LBC182P is qualified at NOT CLASSIFIED NOT CLASSIFIED

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2212-013

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.